Prof. Hongyun So

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Prof. Hongyun So received the B.S. degree from Hanyang University, Korea, in 2009, the M.S. degree from KAIST, Korea, in 2011, and the Ph.D. degree from the University of California, Berkeley, in 2014, all in mechanical engineering. He joined Stanford University in 2015 as a Post-Doctoral Scholar with the Aeronautics and Astronautics Department. He is currently a Professor with the Mechanical Engineering Department, and Vice Director of Advanced Semiconductor Packaging Center, Hanyang University. His research interests include design, modeling, and manufacturing of advanced semiconductor packaging, lab-on-a-chip, harsh-environment sensors, and mechanical issues related to heat transfer and fluid mechanics.